

Serial No. 10/609,400

Docket No. K-0533

Amdt. dated January 4, 2006

Reply to Office Action of October 4, 2005

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A shadow mask for ~~fabricating~~ a flat display, comprising:
a first substrate having a plurality of first via holes formed therein; and
a second substrate positioned on the first substrate, the second substrate having a plurality of second via holes; formed therein, wherein the first via holes and the second via holes are arranged so as to overlap with each other, and ~~the~~ wherein each second via hole has a ~~diameter-width~~ diameter-width greater than a ~~diameter-width~~ diameter-width of ~~the~~ a corresponding first via hole.
2. (Currently Amended) The shadow mask as claimed in claim 1, wherein a thickness ~~of the second substrate has a thickness thicker is greater~~ than a thickness of the first substrate.
3. (Currently Amended) The shadow mask as claimed in claim 2, wherein the first substrate is between approximately 1 [[-]] and 100μm thick, and the second substrate is between approximately 5 [[-]] and 1000μm thick.

4. (Currently Amended) The shadow mask as claimed in claim 1, wherein ~~the each~~ first via hole and ~~the corresponding~~ second via hole have a ~~1-1000 μ m diametric difference in~~ width of between approximately 1 and 1000 μ m.

5. (Currently Amended) The shadow mask as claimed in claim 1, wherein ~~a the~~ plurality of ~~the first via holes are arranged on every column in~~ columns along the first substrate, and ~~one the plurality of second via hole is~~ holes are arranged on every column the second substrate such that each column of first via holes is aligned with one corresponding second via hole.

6. (Original) The shadow mask as claimed in claim 5, wherein the first and second via holes have a form selected from a circle, a polygon, and stripe.

7. (Original) The shadow mask as claimed in claim 1, further comprising a bridge formed on the first substrate between adjacent first via holes.

8. (Currently Amended) The shadow mask as claimed in claim 7, wherein a thickness of the bridge has a thickness is substantially the same ~~with the~~ as a thickness of the second substrate.

9. (Currently Amended) The shadow mask as claimed in claim 7, wherein the bridge is ~~formed across~~ configured to cross the corresponding second via hole.

10. (Currently Amended) A shadow mask for ~~fabricating~~ a flat display, comprising:
a first substrate having a plurality of first via holes formed therein;
a second substrate positioned on the first substrate, the second substrate having a plurality of second via holes formed therein; and
a third substrate positioned on the second substrate, the third substrate having a plurality of third via holes; formed therein, wherein the first, second, and third via holes are arranged so as to overlap with one another, wherein a width of each ~~the~~ second via hole ~~has a diameter is~~ greater than a ~~diameter of the~~ width of a corresponding first via hole, and ~~the~~ wherein a width of each third via hole ~~has a diameter is~~ greater than ~~the diameter of the~~ a width of a corresponding second via hole.

11. (Currently Amended) The shadow mask as claimed in claim 10, wherein a thickness of the second substrate ~~has a thickness thicker is greater~~ than a thickness of the first substrate or a thickness of third substrate.

12. (Currently Amended) The shadow mask as claimed in claim 11, wherein the first ~~substrate or the third~~ substrate is approximately 1 - 100 μ m thick, and the second substrate is approximately 5 - 1000 μ m thick.

13. (Currently Amended) The shadow mask as claimed in claim 10, wherein ~~the each~~ first via hole and ~~the corresponding~~ second via hole, or ~~the each~~ second via hole and ~~the corresponding~~ third via hole, have a difference in width of approximately 1 - 1000 μ m-diametric difference.

14. (Currently Amended) The shadow mask as claimed in claim 10, wherein ~~a the~~ plurality of the first via holes are arranged ~~on every column~~ in columns along the first substrate, and ~~one the plurality of second via holes or the plurality of third via hole is holes~~ are arranged on every column the second and third substrate, respectively, such that each column of first via holes is aligned with one corresponding second via hole or one corresponding third via hole.

15. (Original) The shadow mask as claimed in claim 14, wherein the first, second, and third via holes have forms selected from a circle, a polygon, and stripe.

16. (Original) The shadow mask as claimed in claim 10, further comprising a bridge formed on the first substrate between adjacent first via holes.

17. (Currently Amended) The shadow mask as claimed in claim 16, wherein a thickness of the bridge has a thickness is substantially the same with the as a thickness of the second substrate.

18. (Currently Amended) The shadow mask as claimed in claim 16, wherein the bridge is ~~formed across the~~ configured to cross a corresponding second via hole.

19. (New) The shadow mask as claimed in claim 11, wherein the thickness of the second substrate is greater than the thickness of the first substrate, and also greater than the thickness of the third substrate.

20. (New) The shadow mask as claimed in claim 12, wherein the first and third substrates are each approximately 1-100 μm thick.

21. (New) The shadow mask as claimed in claim 13, wherein each first via hole and corresponding second via hole have a difference in width of approximately 1-1000 μm , and each

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second via hole and corresponding third via hole have a difference in width of approximately 1 - 1000 μ m.

22. (New) The shadow mask as claimed in claim 14, wherein the plurality of second via holes are arranged on the second substrate such that each column of first via holes is aligned with one corresponding second via hole, and the plurality of third via holes are arranged on the third substrate such that each of the plurality of second via holes are aligned with a corresponding third via hole.